

Lab Bonder

Advanced Lab Die Attach & Process Development Platform

Engineered for research at the limits of precision

The T-200 high-end benchtop bonding system is designed for advanced R&D environments where every micron matters. Built for maximum stability and process control, it delivers uncompromising repeatability with sub-micron accuracy, ideal for demanding bonding applications in microelectronics, photonics, and precision assembly.

With its advanced manual and automatic operating modes, the T-200 offers ultimate flexibility, from fast prototyping and iterative lab trials to structured, repeatable processes for validated research workflows. Intuitive handling, high-precision alignment, and reliable process performance make the T-200 a powerful platform for researchers and engineers who need results they can trust.

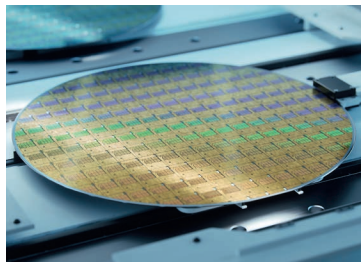


Save lab space - full bonding capability in less than half a square meter

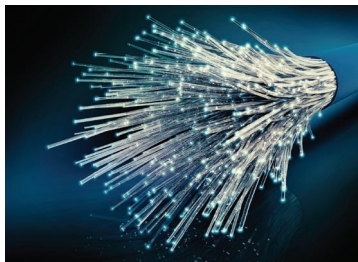
Despite its compact footprint, the T-200 integrates all key bonding processes in one high-performance system, helping you maximize productivity without compromising valuable lab space.



Defense / Military



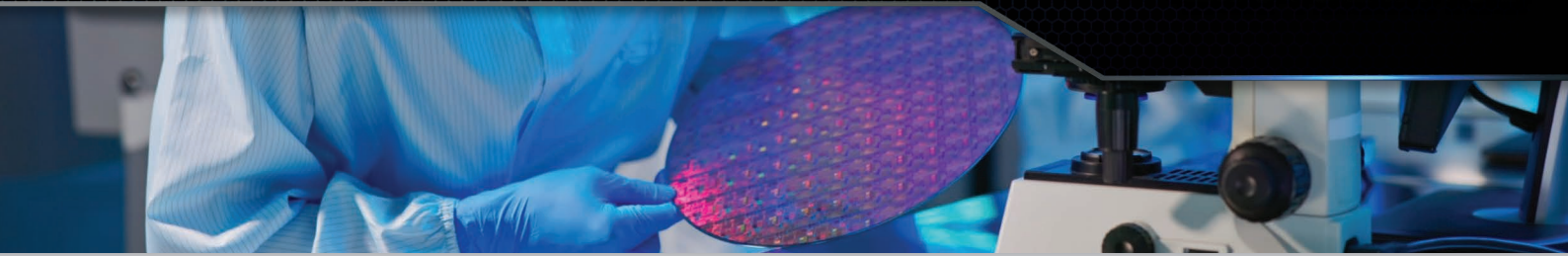
Semiconductor & Microelectronics



Optoelectronics & Photonics



Medtec



Added Value

- Prototype and small volume packaging
- Sub-micron placement accuracy: $\pm 0.7 \mu\text{m}^*$
- Manual and fully automatic operation for R&D and process setup
- High modularity
- Rigid full-granite mainframe with suspended X/Y linear axes
- Direct measuring system in X and Y with $0.001 \mu\text{m}$ resolution
- Optimized for photonics and microelectronics assembly

*accuracy is process dependent

Typical applications:

- Optoelectronics & Photonics
- Semiconductor & Microelectronics
- Medtec
- Defense / Military

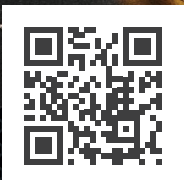
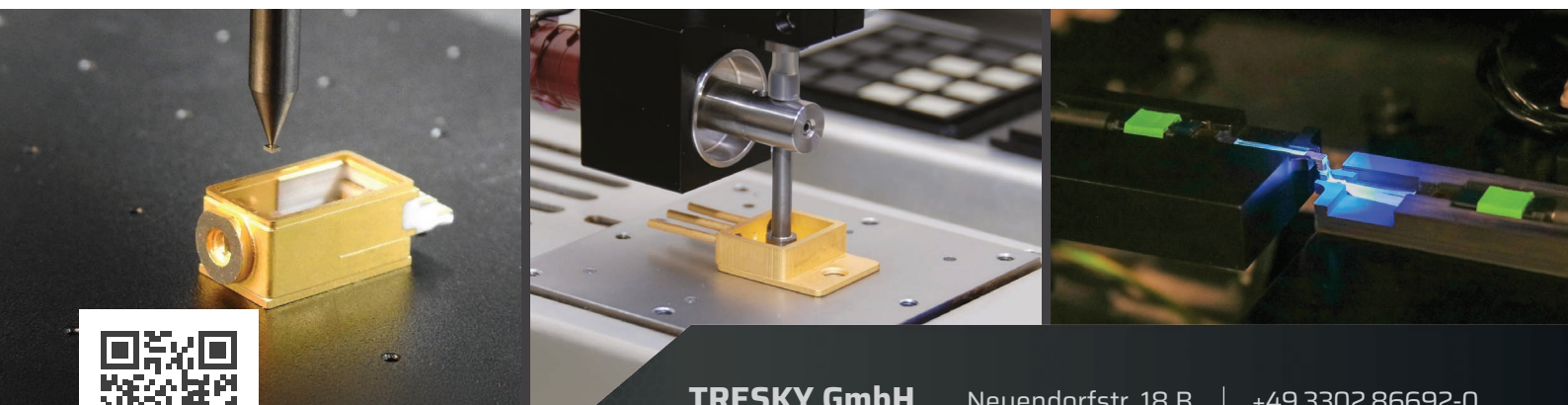
Supported technologies

- Sintering (Ag & Cu)
- Die attach & flip-chip bonding
- Epoxy / UV adhesive bonding
- Solder & eutectic bonding
- Thermocompression bonding
- Prototype assembly and process development
- Ultrasonic Bonding

Core specifications

Working area	200 × 240 mm
Substrate area	400 × 450 mm
Z-Movement	33 mm
Chip Rotation Max.	up to 360°
Bond Force Range	0,01 N up to 350 N*
Footprint	600 x 750 mm

*Up to 1.000 N on request



more information

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